


## TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking							
Application Number : Date : First Named Applicant: Confirmation Number: Attorney Docket Number:	10/050507 2002-01-16 Lee Teck 7687 MTI-31607							
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<table border="1"><thead><tr><th data-bbox="133 993 773 1031">Submitted By:</th><th data-bbox="773 993 1110 1031">Elec. Sign.</th><th data-bbox="1110 993 1412 1031">Sign. Capacity</th></tr></thead><tbody><tr><td data-bbox="133 1031 773 1108">Kristine M Strodthoff Registered Number: 34259</td><td data-bbox="773 1031 1110 1108">/kms/</td><td data-bbox="1110 1031 1412 1108">Attorney</td></tr></tbody></table>			Submitted By:	Elec. Sign.	Sign. Capacity	Kristine M Strodthoff Registered Number: 34259	/kms/	Attorney
Submitted By:	Elec. Sign.	Sign. Capacity						
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Documents being submitted:	Files
us-ids	MTI-31607c-usidst.xml us-ids.dtd us-ids.xsl
Comments	